## SY89859U



Precision Low-Power 8:1 MUX with Internal Termination and 1:2 LVPECL Fanout Buffer

## General Description

The SY89859U is a low jitter, low-power, high-speed 8:1 multiplexer with a 1:2 differential fanout buffer optimized for precision telecom and enterprise server distribution applications. The SY89859U distributes clock frequencies from DC to $>2.5 \mathrm{GHz}$, and data rates to 2.5 Gbps guaranteed over temperature and voltage.
The SY89859U differential input includes Micrel's unique, 3-pin input termination architecture that directly interfaces to any differential signal (AC- or DC-coupled) as small as 100 mV ( 200 mVpp ) without level shifting or termination resistor networks in the signal path. The outputs are $800 \mathrm{mV}, 100 \mathrm{~K}$-compatible LVPECL with extremely fast rise/fall time guaranteed to be less than 180ps.
The SY89859U features a patent-pending isolation design that significantly improves on channel-tochannel crosstalk-induced jitter performance.
The SY89859U operates from a $2.5 \mathrm{~V} \pm 5 \%$ or 3.3 V $\pm 10 \%$ supply and is guaranteed over the full industrial temperature range of $-40^{\circ} \mathrm{C}$ to $+85^{\circ} \mathrm{C}$. The SY89859U is part of Micrel's high-speed, Precision Edge ${ }^{\circledR}$ product line.
All support documentation can be found on Micrel's web site at: www.micrel.com.

United States Patent No. RE44,134
Precision Edge is a registered trademark of Micrel, Inc.

## Features

- Selects between 1 of 8 inputs, and provides 2 precision, low skew 100K-compatible LVPECL output copies
- Low power: 150 mW typ. (2.5V)
- Guaranteed AC performance over temperature and voltage:
- DC to $>2.5 \mathrm{Gbps}$
- DC to $>2.5 \mathrm{GHz}$
- <690ps propagation delay
- <180ps $\mathrm{t}_{\mathrm{r}} \mathrm{l}_{\mathrm{f}}$ time
- <20ps skew (output-to-output)
- Unique, patent-pending channel-to-channel isolation design provides superior crosstalk performance
- Ultra-low jitter design:
- $<1 \mathrm{ps}_{\mathrm{RMS}}$ random jitter
- $<10 p s_{\text {pp }}$ deterministic jitter
- <10pspp total jitter (clock)
- $<1 \mathrm{ps}_{\text {RMS }}$ cycle-to-cycle jitter
- $<0.7 \mathrm{ps}_{\text {RMS }}$ crosstalk-induced jitter
- Unique, patented input termination and VT pin accepts DC- and AC-coupled inputs (CML, PECL, LVDS)
- Power supply $2.5 \mathrm{~V} \pm 5 \%$ or $3.3 \mathrm{~V} \pm 10 \%$
- $-40^{\circ} \mathrm{C}$ to $+85^{\circ} \mathrm{C}$ industrial temperature range
- Available in $44-$ pin ( $7 \mathrm{~mm} \times 7 \mathrm{~mm}$ ) QFN package


## Applications

- Data communication systems
- All SONET/SDH data/clock applications
- All Fibre Channel applications
- All Gigabit Ethernet applications


## Functional Block Diagram



## Ordering Information ${ }^{(1)}$

| Part Number | Package Type | Operating <br> Range | Package Marking | Lead <br> Finish |
| :--- | :---: | :---: | :---: | :---: |
| SY89859UMY | QFN-44 | Industrial | SY89859U with Pb-Free bar-line indicator | Matte-Sn <br> Pb-Free |
| SY89859UMYTR $^{(2)}$ | QFN-44 | Industrial | SY89859U with Pb-Free bar-line indicator | Matte-Sn <br> Pb-Free |

## Notes:

1. Contact factory for die availability. Dice are guaranteed at $\mathrm{T}_{\mathrm{A}}=25^{\circ} \mathrm{C}$, DC Electricals only.
2. Tape and Reel.

## Pin Configuration



## Truth Table

| SEL2 | SEL1 | SELO | Q | IQ |
| :---: | :---: | :---: | :---: | :---: |
| L | L | L | INO | /INO |
| L | L | H | IN1 | /IN1 |
| L | H | L | IN2 | /IN2 |
| L | H | H | IN3 | /IN3 |
| H | L | L | IN4 | /IN4 |
| H | L | H | IN5 | /IN5 |
| H | H | L | IN6 | /IN6 |
| H | H | H | IN7 | /IN7 |

## Pin Description

| Pin Number | Pin Name | Pin Function |
| :---: | :---: | :---: |
| 20, 18 | INO, /INO | Differential Inputs: These input pairs are the differential signal inputs to the device. Inputs accept AC- or DC-coupled signals as small as 100 mV ( 200 mV pp). Each pin of a pair internally terminates to a VT pin through $50 \Omega$. Note that these inputs will default to an indeterminate state if left open. Please refer to the "Input Interface Applications" section for more details. |
| 16, 14 | IN1, /IN1 |  |
| 13, 11 | IN2, /IN2 |  |
| 9, 7 | IN3, /IN3 IN4, /IN4 |  |
| 1, 43 | IN5, /IN5 |  |
| 42, 40 | IN6, IIN6 |  |
| 38, 36 | IN7, IIN7 |  |
| 19, 15 | VT0, VT1 | Input Termination Center-Tap: Each side of the differential input pair terminates to a VT pin. The VT pins provide a center-tap to a termination network for maximum interface flexibility. See "Input Interface Applications" section for more details. For a CML or LVDS inputs, the VT pin is left floating. |
| 12, 8 | VT2, VT3 |  |
| 4, 44 | VT4, VT5 |  |
| 41, 37 | VT6, VT7 |  |
| 17 | VREF-AC0 | Reference Voltage: These outputs bias to $\mathrm{V}_{\mathrm{CC}}-1.2 \mathrm{~V}$. They are used when AC coupling the inputs (IN, /IN). For AC-coupled applications, connect VREF-AC to the VT pin and bypass with a $0.01 \mu$ F low ESR capacitor to VCC. See "Input Interface Applications" section for more details. |
| 10 | VREF-AC1 |  |
| 2 | VREF-AC2 |  |
| 39 | VREF-AC3 |  |
| 21 | SELO | The single-ended TTL/CMOS-compatible inputs select the inputs to the multiplexer. Note that this input is internally connected to a $25 \mathrm{k} \Omega$ pullup resistor and will default to a logic HIGH state if left open. The threshold voltage is $\mathrm{V}_{\mathrm{TH}}=\mathrm{V}_{\mathrm{Cc}} / 2$. |
| 22 | SEL1 |  |
| 35 | SEL2 |  |
| 24, 27, 29, 32 | VCC | Positive Power Supply. Bypass with $0.1 \mu \mathrm{~F} \\| 0.01 \mu \mathrm{~F}$ low ESR capacitors and place as close to each VCC pin as possible. |
| $\begin{aligned} & 25,26 \\ & 30,31 \end{aligned}$ | $\begin{aligned} & \text { Q0, /Q0 } \\ & \text { Q1, /Q1 } \end{aligned}$ | Differential Outputs: These 100K-compatible LVPECL output pairs are the outputs of the device. Unused output pairs may be left open. Each output is designed to drive 800 mV into $50 \Omega$ terminated to $\mathrm{V}_{\mathrm{cc}}-2 \mathrm{~V}$. |
| 23, 28, 33 | GND Exposed Pad | Ground. GND and exposed pad must both be connected to the same ground plane. |

## Absolute Maximum Ratings ${ }^{(1)}$

Supply Voltage ( $\mathrm{V}_{\mathrm{cc}}$ )......................... -0.5 V to +4.0 V
Input Voltage
SELO, SEL1, SEL2 .........................-0.5V to $\mathrm{V}_{\mathrm{cc}}$
INO, /INO, IN1, /IN1,.../IN7, /IN7 ......-0.5V to $\mathrm{V}_{\mathrm{cc}}$
LVPECL Output Current (lout)
Continuous.............................................. $\pm 50 \mathrm{~mA}$
Surge .................................................... $\pm 100 \mathrm{~mA}$
Termination Current
Source or sink current
VT0, VT1, VT2,..VT7............................ $\pm 100 \mathrm{~mA}$
Input Current
Source or sink current
INO, /INO, IN1, /IN1,...IN7, /IN7 ................ $\pm 50 \mathrm{~mA}$
VREF Output Current
VREF-ACO, VREF-AC1..., VREF-AC3....... $\pm 2 m A$
Lead Temperature (soldering, 20 sec .).......... $+260^{\circ} \mathrm{C}$
Storage Temperature $\left(T_{s}\right)$................ $-65^{\circ} \mathrm{C}$ to $150^{\circ} \mathrm{C}$

## Operating Ratings ${ }^{(2)}$



## DC Electrical Characteristics ${ }^{(4)}$

$\mathrm{T}_{\mathrm{A}}=-40^{\circ} \mathrm{C}$ to $+85^{\circ} \mathrm{C}$, unless otherwise stated.

| Symbol | Parameter | Condition | Min | Typ | Max | Units |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| $V_{\text {cc }}$ | Power Supply |  | 2.375 | 2.5 | 2.625 | V |
|  |  |  | 3.0 | 3.3 | 3.6 | V |
| Icc | Power Supply Current | No load, max. V ${ }_{\text {cc }}$ |  | 60 | 85 | mA |
| RIN | Input Resistance (IN-to- $\mathrm{V}_{\mathrm{T}}$ ) |  | 45 | 50 | 55 | $\Omega$ |
| RDIFF_IN | Differential Input Resistance (IN-to-IIN) |  | 90 | 100 | 110 | $\Omega$ |
| $\mathrm{V}_{\mathrm{IH}}$ | Input High Voltage (IN, /IN) | Note 5 | $\mathrm{V}_{\mathrm{cc}}-1.6$ |  | Vcc | V |
| VIL | Input Low Voltage (IN, /IN) |  | 0 |  | $\mathrm{V}_{1 \mathrm{H}}-0.1$ | V |
| $\mathrm{V}_{\text {IN }}$ | Input Voltage Swing (IN, /IN) | See Figure 1a. | 0.1 |  | 1.7 | V |
| VIIFF_IN | Differential Input Voltage Swing \|IN-to-/IN| | See Figure 1b. | 0.2 |  |  | V |
| $\mathrm{V}_{\text {T_IN }}$ | IN-to- $\mathrm{V}_{\mathrm{T}}$ <br> (IN, /IN) |  |  |  | 1.28 | V |
| $V_{\text {REF-AC }}$ | Output Reference Voltage |  | $\mathrm{V}_{\mathrm{cc}}-1.3$ | $\mathrm{V}_{\mathrm{cc}}-1.2$ | $\mathrm{V}_{\mathrm{cc}}-1.1$ | V |

## Notes:

1. Permanent device damage may occur if absolute maximum ratings are exceeded. This is a stress rating only and functional operation is not implied at conditions other than those detailed in the operational sections of this data sheet. Exposure to absolute maximum ratings conditions for extended periods may affect device reliability.
2. The data sheet limits are not guaranteed if the device is operated beyond the operating ratings.
3. Package thermal resistance assumes exposed pad is soldered (or equivalent) to the devices most negative potential on the PCB. $\theta_{\mathrm{JA}}$ and $\Psi_{J B}$ values are determined for a 4-layer board in still-air, unless otherwise stated.
4. The circuit is designed to meet the DC specifications shown in the above table after thermal equilibrium has been established.
5. $\mathrm{V}_{\mathrm{IH}}(\mathrm{min})$ not lower than 1.2 V .

## 100K LVPECL Output DC Electrical Characteristics ${ }^{(6)}$

$\mathrm{V}_{\mathrm{CC}}=+2.5 \mathrm{~V} \pm 5 \%$ or $3.3 \mathrm{~V} \pm 10 \%, \mathrm{R}_{\mathrm{L}}=50 \Omega$ to $\mathrm{V}_{\mathrm{CC}}-2 \mathrm{~V}$; $\mathrm{T}_{\mathrm{A}}=-40^{\circ} \mathrm{C}$ to $+85^{\circ} \mathrm{C}$, unless otherwise stated.

| Symbol | Parameter | Condition | Min | Typ | Max | Units |
| :--- | :--- | :--- | :---: | :---: | :---: | :---: |
| $V_{\text {OH }}$ | Output HIGH Voltage <br> (Q, /Q) |  | $V_{\mathrm{CC}}-1.145$ |  | $\mathrm{~V}_{\mathrm{CC}}-0.895$ | V |
| $\mathrm{~V}_{\text {OL }}$ | Output LOW Voltage <br> (Q, /Q) |  | $\mathrm{V}_{\mathrm{CC}}-1.945$ |  | $\mathrm{~V}_{\mathrm{CC}}-1.695$ | V |
| $V_{\text {OUT }}$ | Output Differential Swing | See Figure 1a. | 550 | 800 |  | mV |
| $V_{\text {DIFF_OUT }}$ | Differential Output Voltage Swing | See Figure 1b. | 1100 | 1600 | mV |  |

## LVTTL/CMOS DC Electrical Characteristics ${ }^{(6)}$

$\mathrm{V}_{\mathrm{CC}}=+2.5 \mathrm{~V} \pm 5 \%$ or $3.3 \mathrm{~V} \pm 10 \% ; \mathrm{T}_{\mathrm{A}}=-40^{\circ} \mathrm{C}$ to $+85^{\circ} \mathrm{C}$, unless otherwise stated.

| Symbol | Parameter | Condition | Min | Typ | Max | Units |
| :--- | :--- | :--- | :---: | :---: | :---: | :---: |
| $\mathrm{V}_{\mathrm{IH}}$ | Input HIGH Voltage |  | 2.0 |  |  | V |
| $\mathrm{~V}_{\mathrm{IL}}$ | Input LOW Voltage |  |  |  | 0.8 | V |
| $\mathrm{I}_{\mathrm{IH}}$ | Input HIGH Current | $\mathrm{I}_{\mathrm{IH}} @ \mathrm{~V}_{\mathrm{IN}}=\mathrm{V}_{\mathrm{CC}}$ | -125 |  | 40 | $\mu \mathrm{~A}$ |
| $\mathrm{I}_{\mathrm{IL}}$ | Input LOW Current | $\mathrm{I}_{\mathrm{IL}} @ \mathrm{~V}_{\mathrm{IN}}=0.5 \mathrm{~V}$ | -300 |  |  | $\mu \mathrm{~A}$ |

Note:
6. The circuit is designed to meet the DC specifications shown in the above table after thermal equilibrium has been established.

## AC Electrical Characteristics ${ }^{(7)}$

$\mathrm{V}_{\mathrm{CC}}=+2.5 \mathrm{~V} \pm 5 \%$ or $3.3 \mathrm{~V} \pm 10 \% ; \mathrm{V}_{\mathbb{I N}} \geq 100 \mathrm{mV}(200 \mathrm{mVpp}) ; \mathrm{R}_{\mathrm{L}}=50 \Omega$ to $\mathrm{V}_{\mathrm{CC}}-2 \mathrm{~V} ; \mathrm{T}_{\mathrm{A}}=-40^{\circ} \mathrm{C}$ to $+85^{\circ} \mathrm{C}$, unless otherwise stated.

| Symbol | Parameter | Condition | Min | Typ | Max | Units |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| $\mathrm{f}_{\text {MAX }}$ | Maximum Operating Frequency |  | 2.5 |  |  | Gbps |
|  |  |  | 2.5 | 3.5 |  | GHz |
| $\mathrm{t}_{\text {pd }}$ | Differential Propagation Delay$\begin{aligned} & \text { IN-to-Q } \\ & \text { SEL-to-Q } \end{aligned}$ |  | 360 | 475 | 640 | ps |
|  |  |  | 200 | 600 | 850 | ps |
| $\mathrm{t}_{\mathrm{pd}}$ <br> Tempco | Differential Propagation Delay Temperature Coefficient | IN-to-Q |  | 300 |  | fs $/{ }^{\circ} \mathrm{C}$ |
|  |  | SEL-to-Q |  | 400 |  |  |
| tskew | Output-to-Output Skew Part-to-Part Skew | Note 8 | 5 |  | 20 | ps |
|  |  | Note 9 |  |  | 200 | ps |
| $\mathrm{t}_{\text {IITTER }}$ | Data <br> Random Jitter (RJ) <br> Deterministic Jitter (DJ) | Note 10 |  |  | 1 | pS ${ }_{\text {RMS }}$ |
|  |  | Note 11 |  |  | 10 | pS ${ }_{\text {PP }}$ |
|  | Clock <br> Cycle-to-Cycle Jitter <br> Total Jitter (TJ) | Note 12 |  |  | 1 | pS ${ }_{\text {RMS }}$ |
|  |  | Note 13 |  |  | 10 | pS ${ }_{\text {Pp }}$ |
|  | Adjacent Channel Crosstalk-induced Jitter | Note 14 |  |  | 0.7 | pS ${ }_{\text {RMS }}$ |
|  | Output Rise/Fall Time (20\% to 80\%) | At full output swing. | 50 | 110 | 180 | ps |

Notes:
7. High-frequency AC-parameters are guaranteed by design and characterization.
8. Output-to-output skew is measured between two different outputs under identical input transitions.
9. Part-to-part skew is defined for two parts with identical power supply voltages at the same temperature and with no skew of the edges at the respective inputs.
10. Random jitter is measured with a K28.7 character pattern, measured at $<f_{\text {MAX }}$.
11. Deterministic jitter is measured at 2.5 Gbps with both K 28.5 and $2^{23}-1$ PRBS pattern.
12. Cycle-to-cycle jitter definition: the variation of periods between adjacent cycles, $T_{n}-T_{n-1}$ where $T$ is the time between rising edges of the output signal.
13. Total jitter definition: with an ideal clock input of frequency $<f_{M A X}$, no more than one output edge in $10^{12}$ output edges will deviate by more than the specified peak-to-peak jitter value.
14. Crosstalk-induced jitter is defined as the added jitter that results from signals applied to two adjacent channels. It is measured at the output while applying two similar, differential clock frequencies that are asynchronous with respect to each other at the inputs.

## Single-Ended and Differential Swings



Figure 1a. Single-Ended Voltage Swing


Figure 1b. Differential Voltage Swing

## Typical Operating Characteristics

$\mathrm{V}_{\mathrm{CC}}=3.3 \mathrm{~V}, \mathrm{GND}=0, \mathrm{~V}_{\mathrm{IN}}=100 \mathrm{mV}(200 \mathrm{mVpp}), \mathrm{R}_{\mathrm{L}}=50 \Omega$ to $\mathrm{V}_{\mathrm{CC}}-2 \mathrm{~V} ; \mathrm{T}_{\mathrm{A}}=25^{\circ} \mathrm{C}$, unless otherwise stated.


## Functional Characteristics

$\mathrm{V}_{\mathrm{CC}}=3.3 \mathrm{~V}, \mathrm{GND}=0, \mathrm{~V}_{\mathrm{IN}}=100 \mathrm{mV}(200 \mathrm{mVpp}), \mathrm{R}_{\mathrm{L}}=50 \Omega$ to $\mathrm{V}_{\mathrm{CC}}-2 \mathrm{~V} ; \mathrm{T}_{\mathrm{A}}=25^{\circ} \mathrm{C}$, unless otherwise stated.



## Input and Output Stages



Figure 2a. Simplified Differential Input Stage


Figure 2b. Simplified LVPECL Output Stage

## Input Interface Applications



For $\mathrm{V}_{\mathrm{CC}}=3.3 \mathrm{~V}, \mathrm{R}_{\mathrm{pd}}=50 \Omega$.

$$
\text { For } \mathrm{V}_{\mathrm{CC}}=2.5 \mathrm{~V}, \mathrm{R}_{\mathrm{pd}}=19 \Omega
$$

Figure 3a. LVPECL Interface (DC-Coupled)


Figure 3d. CML Interface (AC-Coupled)


For 3.3V, $R_{p d}=100 \Omega$.
For $2.5 \mathrm{~V}, \mathrm{R}_{\mathrm{pd}}=50 \Omega$.

Figure 3b. LVPECL Interface (AC-Coupled)


Figure 3e. LVDS Interface

## LVPECL Output Interface Applications

LVPECL has high input impedance, very low output (open emitter) impedance, and small signal swing which result in low EMI. LVPECL is ideal for driving 50 - - and $100 \Omega$-controlled impedance transmission lines. There are several techniques for terminating


Figure 4a. Parallel Thevenin-Equivalent Termination

## Note:

For 2.5 V system, $\mathrm{R} 1=250 \Omega, \mathrm{R} 2=62.5 \Omega$.
the LVPECL output including: Parallel TerminationThevenin Equivalent, Parallel Termination (3Resistor), and AC-Coupled Termination. Unused output pairs may be left floating. However, singleended outputs must be terminated, or balanced.


Figure 4b. Parallel Termination (3-Resistor)
Note:
For 2.5 V system, $\mathrm{Rb}=19 \Omega$.

## Related Product and Support Documentation

| Part Number | Function | Data Sheet Link |
| :--- | :--- | :--- |
| SY58037U | Ultra Precision 8:1 MUX with Internal <br> Termination and 1:2 CML Fanout Buffer | http://www.micrel.com/product-info/products/sy58037u.shtml |
| SY58038U | Ultra Precision 8:1 MUX with Internal <br> Termination and 1:2 LVPECL Fanout Buffer | http://www.micrel.com/product-info/products/sy58038u.shtml |
| SY58039U | Ultra Precision 8:1 MUX with Internal <br> Termination and 1:2 400mV LVPECL Fanout <br> Buffer | http://www.micrel.com/product-info/products/sy58039u.shtml |
| HBW Solutions | New Products and Applications | www.micrel.com/product-info/products/solutions.shtml |

## Package Information



## NOTES :

1. DIMENSIONING AND TOLERANCING CONFORM TO ASME Y14.5M. - 1994.
2. ALL DIMENSIONS ARE IN MILLIMETERS, $O$ IS IN DEGREES.
3. N IS THE TOTAL NUMBER OF TERMINALS.

DIMENSION D APPLIES TO METALLIZED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM TERMINAL TIP. IF THE TERMINAL HAS THE OPTIONAL RADIUS ON THE OTHER END OF THE TERMINAL. THE DIMENSION O SHOULD NOT BE MEASURED IN THAT RADIUS AREA,
$\triangle$ ND AND NE REFER TO THE NUMBER OF TERMINALS ON EACH D AND E SIDE RESPECTIVELY.
6. MAX. PACKAGE WARPAGE IS 0.05 mm .
7. MAXIMUM ALLOWABLE BURRS IS 0.076 mm IN ALL DIRECTIONS.
$\triangle$ PIN 1 ID ON TOP WLL BE LASER MARKED.
$\triangle$ bllateral coplanarity zone applies to the exposed heat sink slug as well as the TERMINALS.
10. THIS DRAWMNG CONFORMES TO JEDEC REGISTERED OUTLINE MO-220


PCB Thermal Consideration for 44-Pin QFN ${ }^{\text {M }}$ Package (Always solder, or equivalent, the exposed pad to the PCB)

## Package Notes:

1. Package meets Level 2 qualification.
2. All parts are dry-packaged before shipment.
3. Exposed pads must be soldered to a ground for proper thermal management.

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